# Halogen-free Low Flow Prepreg

EM-37B(L)



#### **Feature**

Hi-Tg Halogen-free material

Lead-free processing compatible

Good adhesion for rigid-flex board



# **Basic Properties**

Laminate Thickness (0.5 mm)	Test Method	Test	Unit	EM-37B(L)	
Laminate Property	IPC-TM-650	Condition	<b>3</b> 1110		
Glass Transition Temp.	2.4.25	DSC	$^{\circ}$	175	
Decomposition Temp.	2.3.40	TGA	$^{\circ}$	385	
Peel Strength( 0.5 oz)	2.4.8	as receive	lb/in	6.3	
Thermal Stress (288°C /10s)	2.4.13.1	Clad	cycle	>20	
T-260	2.4.24.1	Clad	min	>60	
T-288	2.4.24.1	Clad	min	>60	



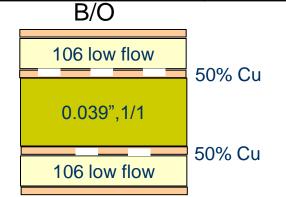
# Reliability Test

N=5

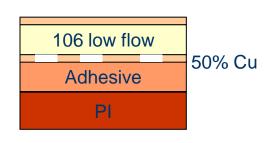
ltem	Unit	SPEC.	EM-37B(L)
Dipping 288°C x 10s (CCL) clad	cycle	10	> 20
Dipping 288°C x 10s (B/O) clad	cycle	10	>20
Dipping 288°C x 10s (PI) clad	cycle	10	>20

CCL

106 x 4plies

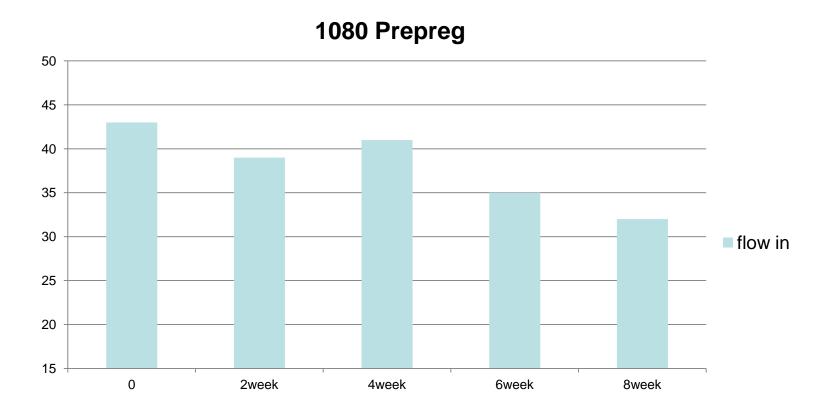


PΙ





## Shelf Life vs. Flow in variation



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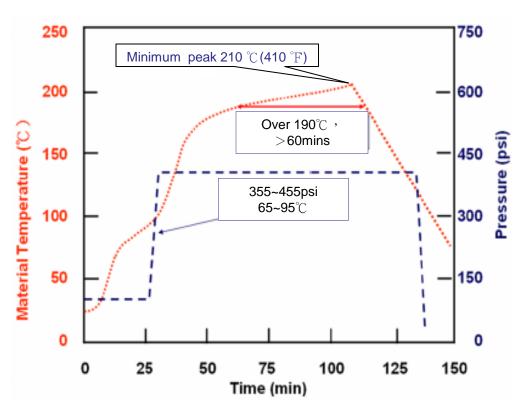
# Shelf Life Test

Item	Unit	Stack	Time				
		up	0 week	2 week	4 week	6 week	8 week
Solder dip 288℃ (n=5)	cycle	106+ 39mil+ 106	> 20	> 20	> 20	> 20	> 20

<sup>※</sup>Prepreg should be stored under 23°C → RH55% for 2 months shelf life.



# Recommend Press Cycle



Heat rate: 2.0~4.0 °C / min

Kiss pressure: 10 kgf / cm<sup>2</sup>

Full pressure: 25 ~ 32 kgf / cm<sup>2</sup>

Apply Full pressure at: 65 ~ 95 ℃

Dwell time: >190 °C / 60 min

(The material peak temperature is

prefer to reach 210℃ for fully curing )



# **Prepreg Specification**

G/F	R/C (%) <sup>1</sup>	Flow In (mil) <sup>2</sup>	V/C (%) <sup>3</sup>	Scale Flow (mil) <sup>4</sup>	THK (mil) <sup>5</sup>
106	72 ± 3	25~80	≦ 1.5	2.2 ± 0.3	2.1
100	75 ± 3	25~80	≦ 1.5	2.5 ± 0.3	2.4
1080 -	65 ± 3	25~80	<b>≦ 1.5</b>	3.2 ± 0.3	3.1
	68 ± 3	25~80	≦ 1.5	3.5 ± 0.3	3.4

1. Resin content: IPC TM-650 2.3.16.1

2. Flow In: refer IPC TM-650 2.3.17.2

3. Volatile content: IPC TM-650 2.3.19

4. Scale Flow: IPC TM-650 2.4.38

5. Thickness measured by micrometer



#### **Conclusion**

# **Advantage of EM-37B(L)**

- Good thermal resistant and adhesion with BO and PI material surface
- Shelf life (RH 55%, < 23 <sup>°</sup>C with 2 months), that could provide stable pressed flow for rigid-flex board application



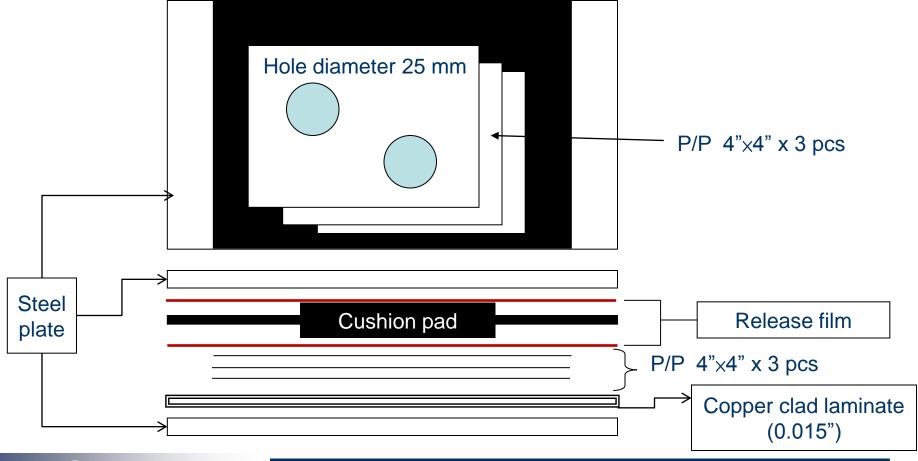
### Flow-in Test Method

Refer to IPC-TM650- 2.3.17.2

**Equipment & Condition Setting** 

Hot press: Temperature 171 ± 2.8°C, press 200±10 psi

Press time: 5 min.



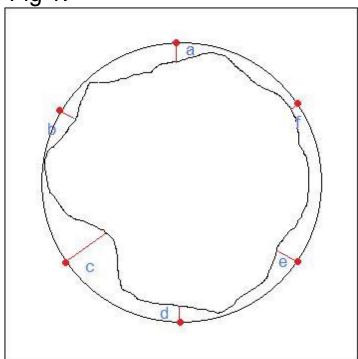


### Flow-in Test Method

#### Calculation

- 1. 2 punched holes (A' & B', diameter = 25mm) in 4" x 4" prepreg
- 2. 3 pcs prepreg are pressed and divided to averaged 6 points with the 2 punched holes respectively as Fig 1.
- 3. Then calculating "Flow-in" data as formula as below

Fig 1.



$$A' = (a+b+c+d+e+f) / 6$$
  
 $B' = (a+b+c+d+e+f) / 6$ 

$$Flow-in = (A'+B') / 2$$